

Chip Scale Review®

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The Future of Semiconductor Packaging

2018 Editorial Calendar

(Editorial close date: 4/21)

July • August

* indicates show distribution

High reliability materials

FO PVD

IoT

System in package

Heterogeneous IC's

AI chip technologies

Smart innovations in MEMS & sensors

RF advanced semiconductor applications

- **ICEPT 2018**
Shanghai, China (Aug 8-11)
- **BITS China 2018**
Shanghai, China (TDB)
- **SEMICON Taiwan ***
Taipei, Taiwan (Sept 5-7)
- **European MEMS & Sensors Summit**
Grenoble, France (Sept 19-21)
- **European Imaging & Sensors Summit**
Grenoble, France (Sept 19-21)
- **Strategic Materials Conference - SMC**
San Jose, CA (Sept 24-26)

Ad Space Close Jun 30 - Ad Materials Close Jul 7

(Editorial close date: 6/9)

September • October

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Fan-out advances

High density flip-chip and advanced CSP

Automotive

Advanced substrates and embedded packaging

WLP

3D TSV for higher performance applications

Lithography

Bonding / Debonding

OSAT market update

- **SMTA International ***
Rosemont, IL (October 16-17)
- **IWLPC-International Wafer-Level Packaging Conference & Exhibition ***
San Jose, CA (Oct 23-25)
- **MEMS & Sensors Executive Congress)**
San Jose, CA (Oct 28-30)
- **International Test Conference (ITC)**
Phoenix, AZ (Oct 31- Nov 2)
- **ITPC**
Maui, Hawaii (Nov 4-7)
- **SEMICON Europa**
Munich, Germany (Nov 13-16)

Ad Space Close Sep 8 - Ad Materials Close Sep 15

(Editorial close date: 9/1)

November • December

* indicates show distribution

5G developments

Test

Metrology

Advanced materials

Flexible electronics

Bumping

Wafer probing

Photonics for next generation applications

Robust interconnects for MEMS sensors

- **EPTC 2018**
Singapore (Dec 4-7)
- **SEMICON Japan**
Tokyo, Japan (Dec 12-14)
- **SEMI European 3D Summit ***
Dresden, Germany (Jan 22-24, 2018)

Ad Space Close Nov 3 - Materials Close Nov 10

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